Proposta di nuova iniziativa (2022-2025)

# Avalanche Diodes Array – 5D (ADA-5D) University of Padova & University of Padova & University of Pavia & IN

University of Padova & INFN Padova University of Pavia & INFN Pavia University of Pisa & INFN Pisa University of Siena & INFN Pisa University of Trento & TIFPA Fondazione Bruno Kessler (FBK – Trento) **CHARGE IDENTIFICATION** of cosmic-ray (CR) ions with charge  $1 \le Z \le 30$  with dE/dx  $\propto Z^2$  measurements in a **charge detector** (SCD) at the top of the instrument

Example of a typical space-borne CR experiment with a generic charge detector (silicon pixels, scintillator paddles/tiles, etc.)

**Backscattering (BS)** from the calorimeter generates fake hits in the charge detectors and in the tracker.

The tracker back estrapolates to the SCD with an impact point IP resolution ~ 150 - 200 um

BS increases with energy and deteriorates the charge ID of individual CR elements.

ADA-5D concept: reject BS with a high resolution ToF measurement



# Charge & Timing 5D detector: x,y,z, charge, time

VERY stringent requirements for a space experiment:

#### Charge measurement:

- large dynamic range > 1000 m.i.p.
- charge resolution for proton < 0.1 => 200-300  $\mu$ m sensors for primary ionization

#### Timing measurement:

- sub-ns resolution (e.g., for 10 - 20 cm flight path  $\rightarrow 100$  ps)

#### Space resolution and granularity:

- modest granularity (3mm x 3mm pixels) to cover large O(m<sup>2</sup>) sensitive area
- an independent TRACKER is in charge of the fine spatial resolution

### Power budget:

- VERY challenging < 150  $W/m^2$ 

### Radiation hardness:

- modest problem for space experiments <  $10^{11}$  1 MeV neq (TID ~100 krad)

Proposed development of LGADs for ADA-5D at FBK

- large pixels (e.g.: 3mm x 3mm)
- sensor thickness 200-300 um

with G~ 10-20 the dominant term for the time resolution is the jitter => 100 ps feasible with a low threshold (realistic as S/N>30 for 1 m.i.p)



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mini-TILE (2.4cm x 2.4 cm): 16 FE = 8 x 8 LGADs



### TILE (9.6 cm x 9.6 cm): 16 mini-tiles = 256 FE = 16 x 8 x 8 = 1024 LGADs





Each FE chip, connected to 4 LGADS, implements:

- double gain linear range to cover > 1000 m.i.p.
- internal ADC
- internal TAC + ADC conversion
- Track & Hold

ID	Task Name	Year 1 Year 2 Year 3 Year 4														
		JFMAMJJAS	OND	JF	MA	MJ	JAS	OND	JF	M A	M	JJ	A S	0	ND	JF
1	WP1 - Phase I															
2	LGAD Simulation and design (FBK)															
3	LGAD 1st batch production @FBK		71													
4	1st batch characterization & delivery		ům-													
5	WP1 - Phase II			-												
6	(mini-)tile design (FBK)				<u> </u>											
7	(mini-)tile production @FBK				Ě		- L	_								
8	2nd batch characterization and delivery						ŭ									
9	WP2 - Phase I			•												
10	FE chip design															
11	FE chip 1st version - production		1													
12	1st FE chip - characterization															
13	FE integration with LGAD test structures		l m													
14	MS-1: fist LGAD array test structure		•	12	21											
15	WP2 - Phase II			-												
16	design of 2nd version of FE chip															
17	production of 2nd version of FE chip			Î				1								
18	integration & test with LGAD array									<b></b>						
19	WP3 - Phase I															
20	design & simulation of 1st digital board															
21	production + electrical tests of 1st board					and and a										
22	WP3 - Phase II			-									•			
23	digital r/o integration LGAD test structure			<b>M</b>				•								
24	design of 2nd version of digital board						ካ		-							
25	production & test of 2nd digital board						4		3							
26	integration & test with LGAD arrays									Y			η			
27	MS-2: LGAD array prototype								12/19							
28	WP4 - Phase I															
29	integration of TIMEPIX3 in beam tracker															
30	CR muon tests with tbeam tracker in lab		_												_	
31	WP4 - Phase II				-				•							
32	source tests with ADA-5D test structures															
33	1st beam test with ADA-5D test structures			Î					1				****			
34	WP4 - Phase III								-							•
35	source tests with prototype													h		
36	2nd beam test with final prototype													1		
37	data analysis								877777	innin	11111		mm	2	enna.	2
38	MS-3: final prototype										l				•	6.20

INFN Padova involved

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# **Developments @ INFN Padova**

### Digital RO board (collaboration with w/ INFN Pisa)

- ADC & TDC information from O(1000) channels
- Small FPGA + fast links

### Fast timing silicon pixel telescope (for test beams)

- Based either on TimePix4 or on TimeSpot
- Synergies with Medipix4/INFN Ferrara & TimeSpot/LHCb being investigated

## Resources @ INFN Padova

- G.Collazuol 20 %
- Michelangelo Pari (PostDoc) 20 %
- Matteo Feltre (PhD) 20%
- Marco Mattiazzi (PhD) 80%

### Richieste:

- Consumo per circa 10kEuro
- Missioni per circa 4kEuro

- Servizi Tecnici ed Elettronici progettazione scheda RO ~ 3m.p.
- Servizio Elettronica programmazione FPGA TP4/TS ~ 3m.p.
- Servizio Progettazione Meccanica setup telescopio ~ 1m.p.
- Servizio Officina Meccanica meccanica telescopio ~ 1m.p.

# Additional material

### Arrival time (ns) of BS from calorimeter on SCD: a GEANT4 simulation



- filled-green: back-scattered photons (create ionizing secondaries → fake hits in SCD);
- filled-blue: back-scattered neutrons;
- filled-orange: back-scattered **electrons** depositing energy in the charge detector;
- filled-red: **incident protons** on charge detector (generated at t=0);
- blue non-filled: histogram inclusive of all above.

#### LARGE AREA DETECTOR concept: N tiles per row x M rows

Example of 1 row equipped with N tiles and readout on either side

ADA-5D goal is limited to the development of one TILE (or mini-TILE)





overlapping staggered layers

	ADA-5D 2023 - FTE	PI/SI	PV	TIFPA	PD
Pier Simone Marrocchesi	PO Univ. di Siena + INFN Gruppo Collegato	0.7			
Paolo Maestro	PA Univ. di Siena + INFN Gruppo Collegato	0.4			
Gabriele Bigongiari	PA Univ. di Siena + INFN Gruppo Collegato	0.6			
Caterina Checchia	Assegno di ricerca - Univ. di Siena - Associaz. INFN Pisa	0.6			
Mina Maghami Moghim	Dottoranda Univ. di Siena - Associaz. INFN Pisa	1.0			
Paolo Brogi	RTDA Univ. di Siena + INFN Gruppo Collegato	0.8			
Francesco Stolzi	RTDA Univ. di Siena + INFN Gruppo Collegato	0.6			
F.Morsani	Tecnologo INFN Pisa	0.1			
Lodovico Ratti	PO Univ. di Pavia		0.3		
Piero Malcovati	PO Univ. di Pavia		0.3		
Marco Grassi	RTDB Univ. di Pavia		0.5		
Joana Minga	Dottoranda (associata sez. Pavia)		1.0		
Simone Giroletti	Dottorando (associato sez. Pavia)		1.0		
Carla Vacchi	RC Univ. di Pavia		0.4		
Lucio Pancheri	PA Univ. di Trento			0.4	
GianFranco Dalla Betta	PA Univ. di Trento			0.1	
Thomas Corradino	Dottorando (associato TIFPA)			0.5	
Alberto Taffelli	Dottorando (associato TIFPA)			0.8	
Maurizio Boscardin	FBK Ricercatore Senior (associato TIFPA)			0.1	
Matteo Centis Vignali	FBK (associato TIFPA)			0.1	
Omar Hammad Ali	FBK (associato TIFPA)			0.2	
Gianmaria Collazuol	PA Univ. di Padova				0.2
Marco Mattiazzi	Dottorando(associato sez. Padova)				0.7
Matteo Feltri	Dottorando(associato sez. Padova)				0.3
TOTALE FTE	11.7	4.8	3.5	2.2	1.2